WHAT IS CLAIMED IS:

1. A method for manufacturing encapsulated electronic components, particularly integrated circuits, at least successively comprising the following steps:

a) attaching electronic components on a first side of a lead frame and electrically connecting said electronic components to said lead frame;

b) using a mould to encapsulate said electronic components with an encapsulating material on just a first side of said lead frame, while a second side of said lead frame is substantially completely shielded with the aid of an adhesive film; and

c) removing said adhesive film and separating, along cutting lines, individual encapsulated electronic components,

wherein bonding of said adhesive film to said second side to be shielded of said lead frame takes place between step a) and step b).

2. The method according to claim 1, wherein said adhesive film is bonded to said lead frame just prior to insertion into said mould.

3. The method according to claim 1, wherein said adhesive film is introduced into said mould, after which said lead frame with said electronic components is bonded with its second side onto said adhesive film.

4. The method according to claim 1, wherein said bonding of said adhesive film to said lead frame is effected with the use of a press-on part which comprises press-on projections that are to be aligned with said cutting lines.

5. The method according to claim 4, wherein a press-on part is used which comprises suitably shaped recesses for said individual electronic components, bridges between said recesses forming said press-on projections.

6. The method according to claim 1, wherein said adhesive film comprises a base film and an adhesive layer, said adhesive layer comprising a material which becomes adhesive as a result of an increase in temperature, and that said adhesive film is increased in temperature, allowing said lead frame to be bonded to said adhesive film.

7. The method according to claim 6, wherein said adhesive layer comprises modified polyethylene terephthalate.

8. The method according to claim 6, wherein the thickness of said adhesive layer is less than 5 micrometers.

9. The method according to claim 1, wherein in step b) at least two electronic components per mould cavity are encapsulated.

10. The method according to claims 6, wherein, in step c), said adhesive film is removed by suitable heating means which heat said film.

11. An adhesive film, at least comprising a base film and modified polyethylene terephthalate, for use in a method according to claim 7.

12. A press-on part designed for use in the method according to claim 4, wherein said press-on part comprises a flat steel plate which is provided with suitably shaped recesses for accommodating electronic components while said lead frame is pressed onto said adhesive film.